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TITLE: FORMING METHOD FOR END SURFACE ELECTRODE  
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ABSTRACT:

PURPOSE: To prevent moisture from infiltrating from a common terminal by coating conductive paste which couples the lead of the common terminal on the end surface, making the paste to creep the upper and lower surfaces of a flat package to form end electrodes, thereby enabling to mount in a stereoscopic structure.

CONSTITUTION: An electronic part such as IC chip 3 or the like is connected by bondings 6, 7 to the common terminal 5 of a metal plate via wirings 4, molded at the lead 5a of the terminal 5 in the state led to the end surface,

and a flat package 8 is composed. Conductive paste is coated to couple the end electrodes 9 to the lead 5a of the terminal 5, and the passage is crept not only to the end surface but to the upper and lower surfaces of the package 8. Thereafter, conductors 10, 11 are formed, for example, on the upper surface electrode 9a of the prescribed electrode 9, and a resistor 12 is printed therebetween.

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